

SID

Factory: Rot am See

Article:

ML2

Provided:

Customer:

Date:

28.04.2026

WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
---------------	----------	----	---------	------------------

C-RS Panasonic R-F770-ED 18-50-00

50200950

18
50

VS



A-RAS-FR4-PP-106-H72-TG170-LowFlow-EM...

50203100

50
----

2

A01

B-RS-FR4-ML-0.711mm-018+018-TG150-HF-...

50203033

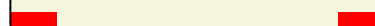
0
711
0

L2

3

A02

L3



B00

C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...

50202996

50
----

4

A-RS Kupferfolie-018my 330x490mm

50200238

18
----

RS



Thickness after Pressing

B00:

890 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

990 µm

Dmin:

790 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1000 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

1100 µm

Dmin:

900 µm

Measuring point:

(05) over SM and galv. Cu; both sides

nominal:

897 µm

Version 1.2.20.35

© Würth Elektronik